



Material Content Data Sheet



Sales Product Name		SAF-XC822M-1FRI AA		Issued		22. January 2018		
MA#		MA001340700						
Package		PG-TSSOP-16-1		Weight*		60.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.168	5.28	5.28	52756	52756
leadframe	non noble metal	nickel	7440-02-0	8.109	13.50		135045	
	non noble metal	iron	7439-89-6	11.199	18.65	32.15	186491	321536
wire	noble metal	gold	7440-57-5	0.300	0.50	0.50	5004	5004
encapsulation	organic material	carbon black	1333-86-4	0.103	0.17		1718	
	plastics	epoxy resin	-	4.366	7.27		72714	
	inorganic material	silicondioxide	60676-86-0	29.912	49.81	57.25	498122	572554
leadfinish	non noble metal	tin	7440-31-5	0.915	1.52	1.52	15234	15234
plating	noble metal	silver	7440-22-4	0.856	1.43	1.43	14261	14261
glue	plastics	acrylic resin	-	0.246	0.41		4104	
	noble metal	silver	7440-22-4	0.874	1.46	1.87	14551	18655
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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